

Patent

Attorney's Docket No.: P17196

Unknown

3743

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner:

Art Unit:

In Re the Patent Application of:

James Christopher Matayabas, Jr.

Application No.: 10/670,699

Filed: September 24, 2003

Title: THERMAL INTERFACE MATERIAL WITH ALIGNED CARBON NANOTUBES

Commissioner for Patents P.O. Box 1450 Alexandria VA 22131-1450

## INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement is being submitted under 37 C.F.R. §1.97(b). Enclosed is a copy of Information Disclosure Citation Form PTO-1449 together with a copy of the patents cited on that form. It is respectfully requested that the cited patents be considered and that the enclosed copy of Information Disclosure Citation Form PTO-1449 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s).

Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure

Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

No fees are associated with this communication. The Commissioner of Patents and Trademarks is hereby authorized to charge any fees associated with this communication or credit any overpayment to Deposit Account No. 50-0221. This document is being provided in duplicate.

Respectfully submitted,

Dated: ン/

Michael D. Pfimier Reg. No. 43,004

Intel Corporation P.O. Box 5326 Santa Clara, CA 95056-5326 (503) 264-7125

## FIRST CLASS CERTIFICATE OF MAILING

37 C.F.R. § 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria VA,

22313-1450 on <u>5/15/05</u>

Name:

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